PCB Specifications: Size:

• 55.5x49.5 mm

Class: 8C

Track width: $>= 0.2~\mathrm{mm}$

Insulation distance: >= 0.1 mm

Minimum drill size: >= 0.4 mm (finished metalized hole: 0.3 mm)

Minimum slot width: >= 1.5 mm

Ring collar: >= 0.1 mm

Stackup:

			Thickness			Loss
Name	Type	Color	$[\mu m]$	Material	Er	tan
F.SilkS	Top Silk					
	Screen					
F.Paste	Top Solder					
	Paste					
F.Mask	Top Solder		10			
	Mask					
F.Cu	copper		35			
dielectric 1	prepreg		100	FR4	4.5	0.020
In1.Cu	copper		35			
dielectric 2	core		1140	FR4	4.5	0.020
In2.Cu	copper		35			
dielectric 3	prepreg		100	FR4	4.5	0.020
B.Cu	copper		35			
B.Mask	Bottom		10			
	Solder					
	Mask					
B.Paste	Bottom					
	Solder					
	Paste					
B.SilkS	Bottom					
	Silk Screen					

Materials:

- FR4, 1.5 mm
- None
- 4 layers
- 35 µm copper thickness

Solder mask:

- TOP / BOTTOM
- \bullet Green

Marking:

- Silk: White

Other markings: